

Data Sheet

Description

The SJPL-H2 is a fast recovery diode of 200 V / 2.0 A. The maximum $t_{\rm rr}$ of 50 ns is realized by optimizing a life-time control.

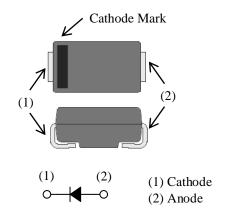
Features

•	V _{RM} 2	00	V
	I _{F(AV)} 2		
	V _F 0.		
	t _{rr1}	-	

- Bare Lead Frame: Pb-free (RoHS Compliant)
- Flammability: Equivalent to UL94V-0
- Suitable for High Reliability and Automotive Requirement.

Package

SJP



Not to scale

Applications

- White Goods
- Audiovisual Equipment
- Lighting Equipment
- Industrial Electronic Equipment (Communication Equipment and Factory Automation)
- Secondary-side Rectifier Diode (Flyback Converter, LLC Converter, etc.)
- Freewheel Diode (Offline Buck Converter, Offline Buck-boost Converter, etc.)

Absolute Maximum Ratings

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Rating	Unit
Nonrepetitive Peak Reverse Voltage	V _{RSM}		200	V
Repetitive Peak Reverse Voltage	V_{RM}		200	V
Average Forward Current	I _{F(AV)}	See Figure 2 and Figure 3	2.0	A
Surge Forward Current	I_{FSM}	Half cycle sine wave, positive side, 10 ms, 1 shot	25	A
I ² t Limiting Value	I ² t	$1 \text{ ms} \le t \le 10 \text{ ms}$	3.1	A^2s
Junction Temperature	T_{J}		-40 to 150	°C
Storage Temperature	T_{STG}		-40 to 150	°C

Electrical Characteristics

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage Drop	V_{F}	$T_J = 25 ^{\circ}\text{C}, I_F = 2.0 \text{A}$	_	_	0.98	V
Forward Voltage Drop		$T_J = 100 ^{\circ}\text{C}, I_F = 2.0 \text{A}$		0.79	_	V
Reverse Leakage Current	I_R	$V_R = V_{RM}$	_	_	50	μA
Reverse Leakage Current under High Temperature	$H \cdot I_R$	$V_R = V_{RM}$, $T_J = 150$ °C	_		200	μΑ
Daniera Danasau Tima	t _{rr1}	$I_F = I_{RP} = 100 \text{ mA},$ 90% recovery point, $T_J = 25 \text{ °C}$	_	_	50	ns
Reverse Recovery Time	t _{rr2}	$I_F = 100$ mA, $I_{RP} = 200$ mA, 75% recovery point, $T_J = 25$ °C	_	—	35	ns
Thermal Resistance (1)	R _{th(J-L)}				20	°C/W

Mechanical Characteristics

Parameter	Conditions	Min.	Тур.	Max.	Unit
Package Weight		_	0.072		g

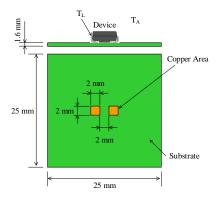
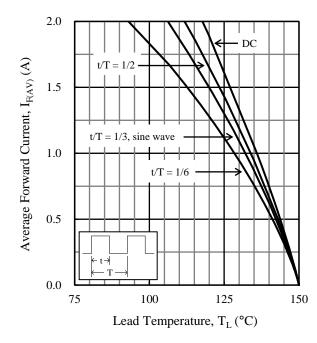
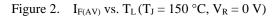


Figure 1. Lead Temperature Measurement Conditions

 $^{^{(1)}}R_{th\,(J-L)}$ is thermal resistance between junction and lead. Lead temperature (T_L) is measured near the root of pin (see Figure 1).

Derating Curves





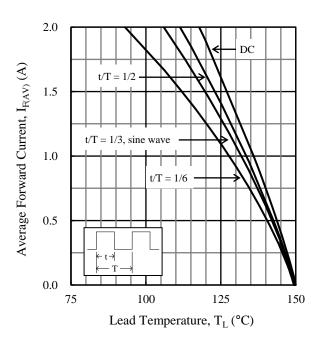


Figure 3. $I_{F(AV)}$ vs. T_L ($T_J = 150$ °C, $V_R = 200$ V)

Characteristic Curves

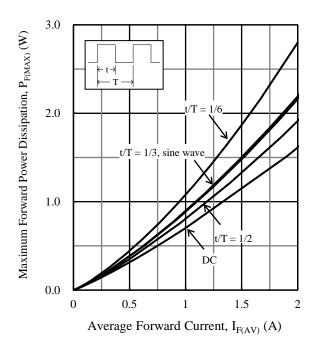


Figure 4. $P_{F(MAX)}$ vs. $I_{F(AV)}$ ($T_J = 150$ °C)

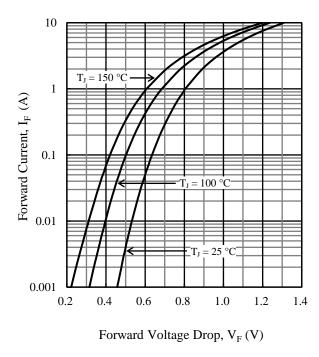


Figure 6. Typical Characteristics: I_F vs. V_F

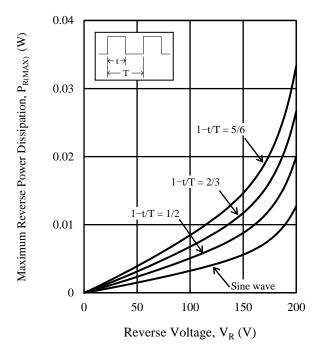


Figure 5. $P_{R(MAX)}$ vs. V_R ($T_J = 150$ °C)

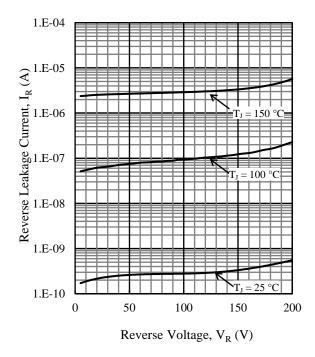


Figure 7. Typical Characteristics: I_R vs. V_R

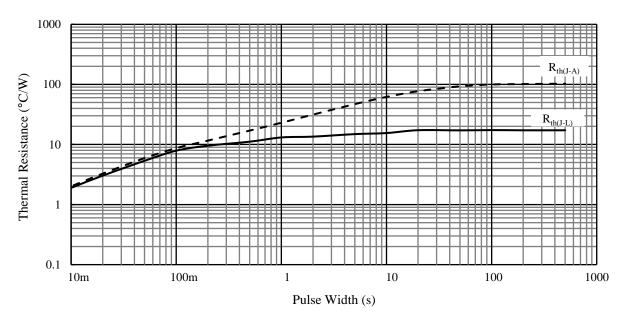
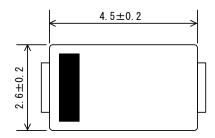
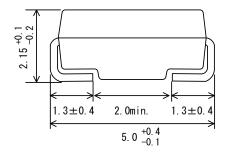


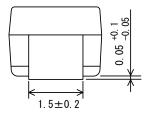
Figure 8. Typical Transient Thermal Resistance Characteristics

Physical Dimensions

• SJP Package







NOTES:

- Dimensions in millimeters
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:

Flow: $260 \, {}^{\circ}\text{C} \, / \, 10 \, \text{s}, \, 1 \, \text{time}$

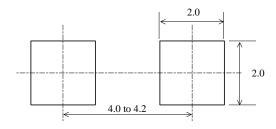
Reflow:

Preheat: 150 °C to 200 °C / 60 s to 120 s

Solder heating: 255 °C / 30s, 3 times (260 °C peak)

Soldering Iron: 350 °C / 3.5 s, 1 time

• SJP Land Pattern Example



NOTE:

- Dimensions in millimeters

Marking Diagram

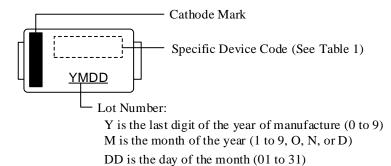


Table 1. Specific Device Code

Specific Device Code	Part Number	
LH2	SJPL-H2	

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